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ABSTRACT OF THE DISCLOSURE

5 A semiconductor chip defines an active surface on which
a plurality of signal pads, a plurality of power source pads
and a plurality of grounding pads are provided. A flexible
insulation substrate defines an opening section by removing
a section of the insulation member, and a power source
conductor pattern and a grounding conductor pattern are
formed to extend across the opening section. The power
source conductor pattern and the grounding conductor pattern
10 are provided with connection branches that are narrower than
power source pads and grounding pads.